

**RJ45C5 R1U 1.7N4G/Y RL****Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



The product range encompasses the following designs:

- 90°, lying (horizontal) and 180°, standing (vertical)
- latch up / latch down
- THT, THR or SMD soldering processes
- Wide range of different design types, also with integrated LEDs and shield contact tabs
- Performance category Cat. 3 to Cat. 6
- Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
- Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
- Dielectric strength  $\geq 1500$  V AC RMS (2250 V AC peak value) according to IEEE 802.3
- Dielectric strength  $\geq 1500$  V AC (peak value) or  $\geq 1500$  V DC according to IEC 60603

Properties and advantages:

- Extended temperature range of  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  for maximum performance
- Reinforced gold layer (30 $\mu\text{m}$ ) for improved corrosion protection
- At least 0.3mm stand-off ensures a perfect soldering result

**General ordering data**

Version	PCB plug-in connector, RJ45 jacks, THT/THR solder connection, 90°, Latch option: top, LED: Yes, green, yellow, Number of poles: 8, Tape
Order No.	<a href="#">2626090000</a>
Type	RJ45C5 R1U 1.7N4G/Y RL
GTIN (EAN)	4050118630183
Qty.	240 pc(s).
Packaging	Tape

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## Technical data

## Dimensions and weights

Depth	15.7 mm	Depth (inches)	0.618 inch
Height	13.1 mm	Height (inches)	0.516 inch
Height of lowest version	16.5 mm	Width	16.4 mm
Width (inches)	0.646 inch	Net weight	8.408 g

## System specifications

Colour of left LED	green	Colour of right LED	yellow
Forward current	20 mA	Forward voltage, max.	2.6 V
Forward voltage, min.	1.8 V	LED	Yes
Latch option	top	Mounting onto the PCB	THT/THR solder connection
Number of poles	8	Outgoing elbow	90°
Pitch in inches (P)	0.04 "	Pitch in mm (P)	1.02 mm
Plugging cycles	750	Product family	OMNIMATE Data - RJ45 modular jack
Protection degree	IP20	Shield surface	nickel-plated
Shielding	Yes	Solder pin dimensions	Octagonal
Solder pin length (l)	1.7 mm	Soldering process	Reflow soldering, Manual soldering, Wave soldering
Tolerance of solder pin position	± 0.1 mm	Type of connection	Solder connection

## Electrical properties

Dielectric strength, contact / contact	1000 V DC	Dielectric strength, contact / shield	1500 V DC
Insulation strength	≥ 500 MΩ	PoE / PoE+	conforming to IEEE 802.3at
Rated current	1.5 A	Rated voltage	125 V

## Material data

Insulating material	PA 9T	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	II
Insulation strength	≥ 500 MΩ	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact base material	Phosphor bronze alloy
Contact material	Cu-alloy	Contact surface	Gold over nickel
Storage temperature, min.	-40 °C	Storage temperature, max.	85 °C
Operating temperature, min.	-40 °C	Operating temperature, max.	85 °C

## Packing

Packaging	Tape	VPE length	359 mm
VPE width	354 mm	VPE height	128 mm

## Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01

## Approvals

ROHS	Conform
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## Technical data

### Downloads

Approval/Certificate/Document of Con-  
formity

[Certificate of Compliance](#)

Catalogues

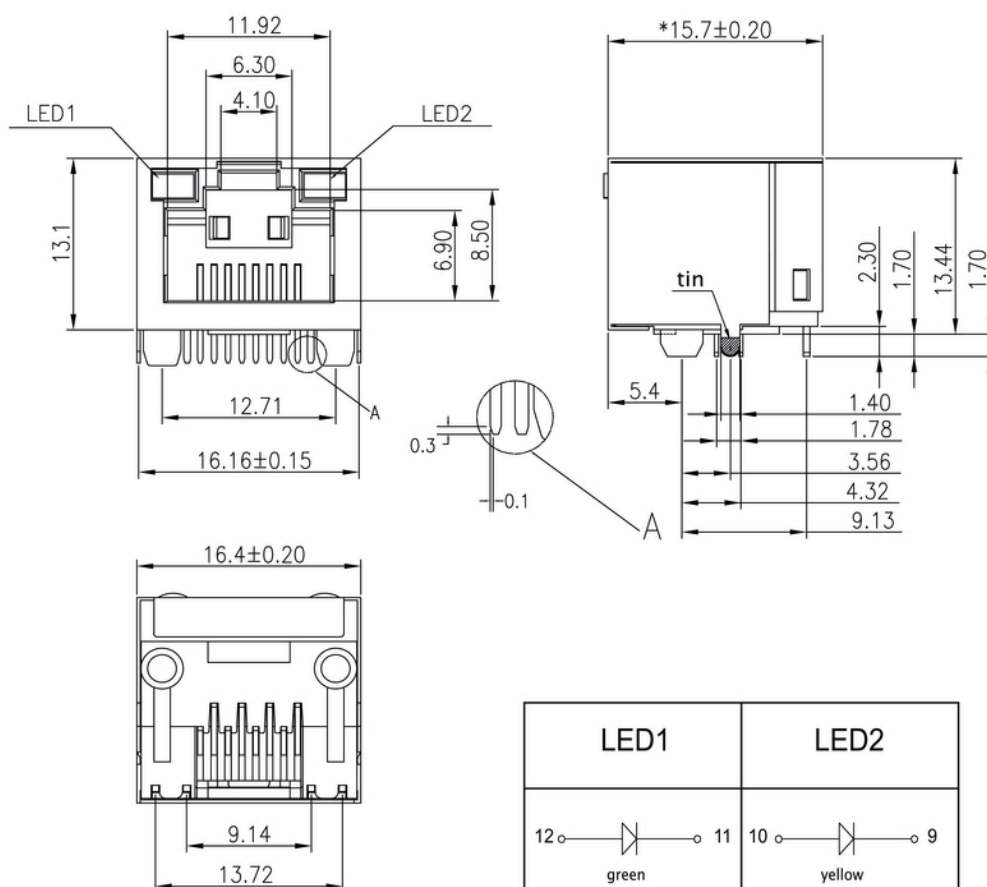
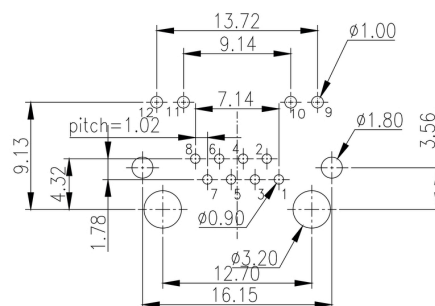
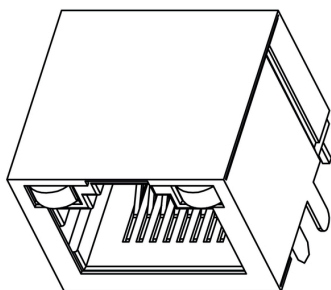
[Catalogues in PDF-format](#)

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## Drawings



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**Drawings**

RJ45	G1	R	1	U	3.2	E	4	GY/GY	TY	RJ45G1 R1U 3.2E4GY/GY TY
										<b>Packaging</b>
										<b>TY</b>
										<b>RL</b>
										Tray in box (manual assembly)
										Tape on <b>Reel</b> (automated assembly)
										<b>LED</b>
										<b>Y/G</b>
										Yellow/Green
										<b>G/Y</b>
										Green/Yellow (standard)
										<b>GY/GY</b>
										Green-Yellow/Green-Yellow
										<b>O/G</b>
										Orange/Green
										<b>R/O</b>
										Red/Orange
										... (further combinations possible)
										<b>N</b>
										without LED
										<b>Contact surface thickness</b>
										<b>4</b>
										1 = 3µ", 2 = 6µ", 3 = 15µ", 4 = 30µ", 5 = 50µ"
										<b>EMI tabs (ground fingers)</b>
										<b>E</b>
										E = with EMI tabs
										<b>N</b>
										N = without EMI tabs
										<b>Solder Pin length</b>
										<b>3.2</b>
										3.2 mm
										<b>1.6</b>
										1.6 mm
										<b>D</b>
										SMD
										<b>Direction, latch style</b>
										<b>U</b>
										Horizontal (90°, side entry), latch up
										<b>D</b>
										Horizontal (90°, side entry), latch down
										<b>V</b>
										Vertical (180°, top entry)
										<b>Y</b>
										Diagonal (45°), latch up
										<b>Number of Ports</b>
										<b>1</b>
										1 Port
										<b>12; 14; ...</b>
										multi ports side by side, Multiport
										<b>21; 41; ...</b>
										multi ports about each other, Multilevel
										<b>Assembly on PCB</b>
										<b>R</b>
										Through Hole Reflow - THR
										Soldering process: Wave or Reflow soldering
										<b>S</b>
										Surface Mount Technology - SMT
										Soldering process: Reflow soldering
										<b>T</b>
										Through Hole Technology - THT
										Soldering process: Wave
										<b>Performance Category</b>
										<b>C5</b>
										Category 5
										<b>C6</b>
										Category 6
										<b>C6A</b>
										Category 6A
										<b>C5e</b>
										Category 5e
										<b>M</b>
										10/100 Mbit
										<b>G1</b>
										10/100/1000 Mbit
										<b>G10</b>
										10 Gbit
										<b>U</b>
										Unshielded
										<b>MP</b>
										10/100 Mbit with POE
										<b>MP+</b>
										10/100 Mbit with POE+

## Legend

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Catalogue status 04.05.2024 / We reserve the right to make technical changes.

## Recommended wave soldering profiles

**Weidmüller Interface GmbH & Co. KG**  
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Fon: +49 5231 14-0  
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### Single Wave:



### Double Wave:



### Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

## Recommended reflow soldering profile

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## Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically  $\leq +3\text{K/s}$ . In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at  $\geq -6\text{K/s}$  solder is cured. Board and components cool down while avoiding cold cracks.